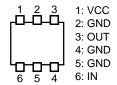




MARKING DIAGRAM



PIN DESCRIPTION



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

V _{CC}	Supply Voltage	6	V
Icc	Circuit Current	40	mA
P _D	Allowable Power Dissipation	280	mW
Topr	Operating Temperature	-40 to +85	°C
Tstg	Storage Temperature	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS (Ta = 25°C)

		Ratings			
Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	4.5	5	5.5	V
Topr	Operating Ambient Temperature	-40	+25	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NOTE: Pay attention to handling since it is liable to be affected by static electricity due to the high frequency process adopted.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C, V_{CC} = 5 V, Z_{S} = Z_{L} = 50 Ω)

			Ratings			
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{CC}	Circuit Current		14.0	19.0	25.0	mA
Gp	Power Gain	f = 1 GHz	24.0	26.5	29.0	dB
		f = 2.2 GHz	24.0	27.0	30.0	1
ISL	Isolation	f = 1 GHz	31.0	33.0	-	dB
		f = 2.2 GHz	31.0	33.0	-	1
RLin	Input Return Loss	f = 1 GHz	12.0	20.0	-	dB
		f = 2.2 GHz	10.0	14.0	-	1
RLout	Output Return Loss	f = 1 GHz	12.0	20.0	-	dB
		f = 2.2 GHz	10.0	16.0	-	1
NF	Noise Figure	f = 1 GHz	_	4.7	5.3	dB
		f = 2.2 GHz	_	4.7	5.3	1
Po(1dB)	Gain 1 dB Compression Output Power	f = 1 GHz	6.0	8.2	-	dBm
		f = 2.2 GHz	4.0	5.7	-	1
fu	Upper Limit Operating Frequency	3 dB down below flat gain at f = 1 GHz	_	3.3	-	GHz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Test Circuit

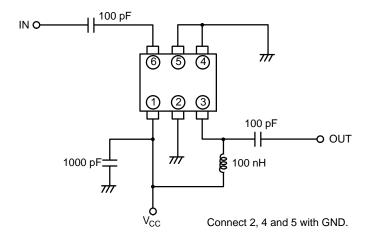
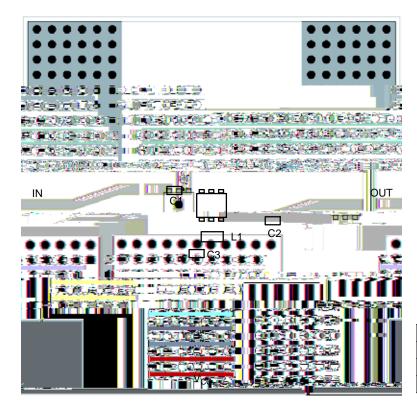


Figure 1. Test Circuit

Design of the Evaluation Board



Symbol	Value	
C1, C2	100 pF	
C3	1000 pF	
L1	100 nH	

Figure 2. Design of the Evaluation Board

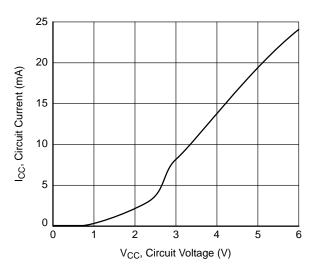
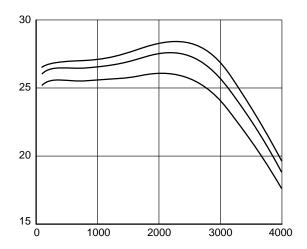
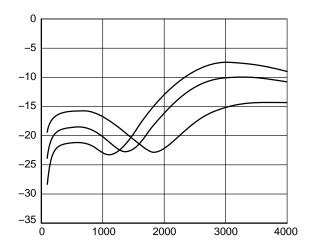
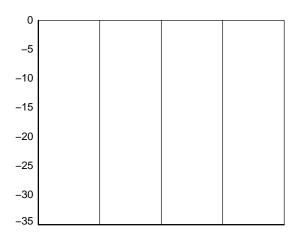


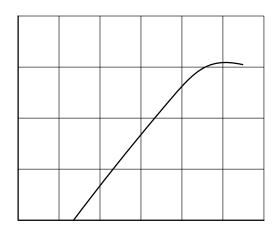
Figure 3. I_{CC} – V_{CC}

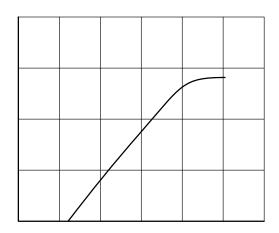
SMA3103







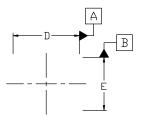






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DATE 28 SEP 2022



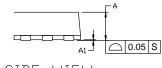
NOTES:

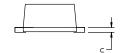
- 1. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- 3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND THE BAR PROTRUSIONS.

DIM	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
А	0.80	0.85	0.90	
A1	0.00		0.02	
b	0.25	0.30	0.40	
C	0.12	0.15	0.25	
D	1.94	2.00	2.06	
Е	1.54	1.60	1.66	
He	2.05	2.10	2.15	
L	0.19	0.25	0.31	
L1	0.00	0.07	0.12	
			·	

⊕ 0.1M A

TOP VIEW





SIDE VIEW

FRONT VIEW



BOTTOM VIEW

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code ■ = Pb–Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

